

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

Claims 1-27 (canceled).

28. (original) A chip manufacturing method, said method comprising:

forming a plurality of elements on a wafer, each element bounded by its respective contours, and each element having at least one edge with a concave shape recessed in one direction; and

cutting out said plurality of elements from said wafer to obtain chips each comprising an individual element.

29. (original) The chip manufacturing method as claimed in claim 28, wherein said chips are cut from said wafer using laser beam.

30. (original) The chip manufacturing method as claimed in claim 28, wherein said chips are cut from said wafer using an ultrasonic vibration tool.

31. (original) The chip manufacturing method as claimed in claim 28, wherein said chips are cut from said wafer using hydraulic pressure.

32. (original) The chip manufacturing method as claimed in claim 28, wherein dicing is used to cut the straight-line portions of the contours of said elements.

33. (original) The chip manufacturing method as claimed in claim 28, further comprising mounting a plate on at least a portion of said chip.

34. (original) A chip manufacturing method, said method comprising:  
cutting out a first chip having at least one edge with a concave shape recessed in one direction;  
cutting out a second ship having a contour that is substantially similar to the contour of said first chip; and  
bonding said first chip to said second chip.

35. (original) The chip manufacturing method as claimed in claim 34, wherein said first chip and said second chip are bonded together using an adhesive.

36. (original) The chip manufacturing method as claimed in claim 34, wherein:  
said first chip is cut from a first wafer; and  
said second chip is cut from a second wafer.